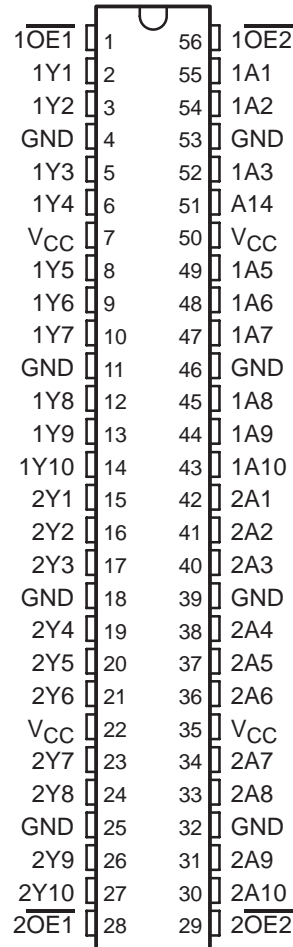


SN54ABT162827, SN74ABT162827 20-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- Members of the Texas Instruments *Widebus*™ Family
- State-of-the-Art *EPIC-II B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54ABT162827 . . . WD PACKAGE
SN74ABT162827 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'ABT162827 are noninverting 20-bit buffers composed of two 10-bit buffers with separate output-enable signals. For either 10-bit buffer, the two output-enable ($\overline{1OE1}$ and $\overline{1OE2}$ or $\overline{2OE1}$ and $\overline{2OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, \overline{OE} inputs should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT162827 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT162827 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT162827 is characterized for operation from -40°C to 85°C .

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SN54ABT162827, SN74ABT162827

20-BIT BUFFERS/DRIVERS

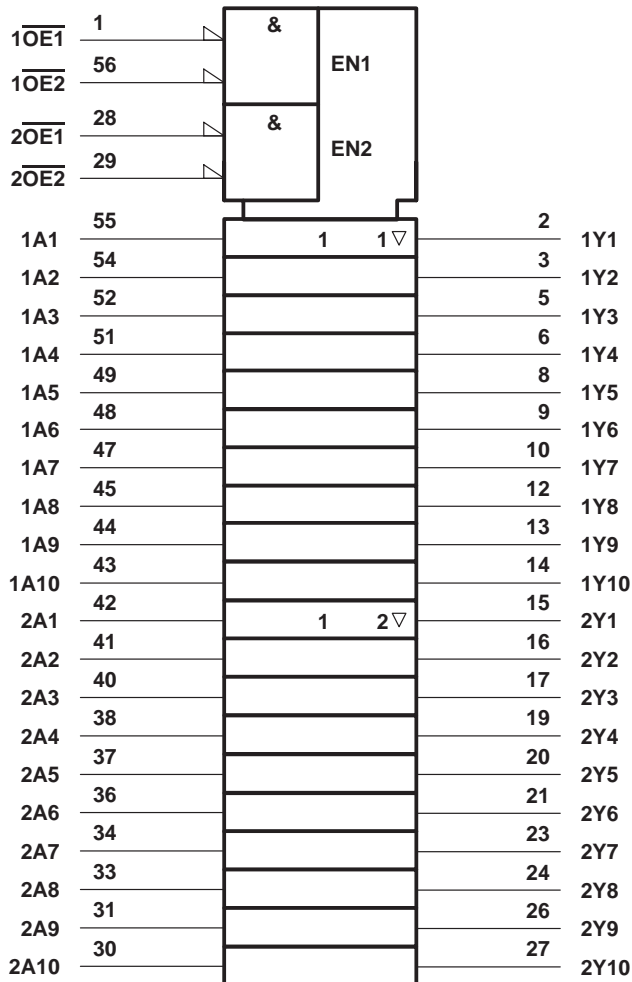
WITH 3-STATE OUTPUTS

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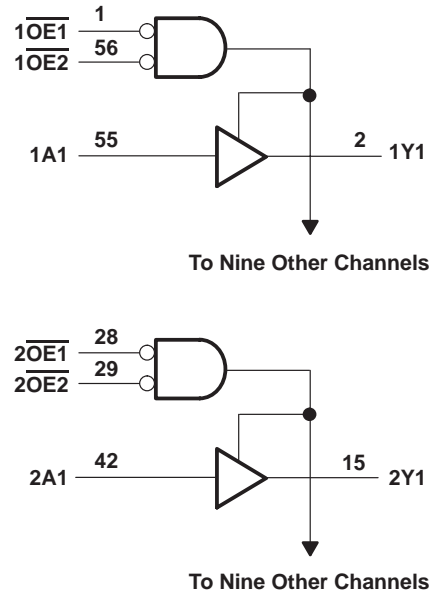
FUNCTION TABLE
(each 10-bit buffer)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54ABT162827, SN74ABT162827 20-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DGG package	1 W
DL package	1.4 W
Operating free-air temperature range, T_A : SN54ABT162827	–55°C to 125°C
SN74ABT162827	–40°C to 85°C
Storage temperature range	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ABT162827		SN74ABT162827		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–12		–12	mA
I_{OL}	Low-level output current		12		12	mA
$\Delta t/\Delta V$	Input transition rise or fall rate	Control inputs		9		ns/V
		Data inputs		10		
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		$\mu\text{s}/\text{V}$
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused or floating inputs must be held high or low.

SN54ABT162827, SN74ABT162827

20-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			SN54ABT162827		SN74ABT162827		UNIT	
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA		-1.2			-1.2		-1.2		V	
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -1 mA		2.5			2.5		2.5		V	
	V _{CC} = 5 V, I _{OH} = -1 mA		3			3		3			
	V _{CC} = 4.5 V	I _{OH} = -3 mA	2.4			2.4		2.4			
I _{OH} = -12 mA		2			2		2				
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 8 mA	0.4 0.8			0.8		0.65		V	
		I _{OL} = 12 mA						0.8			
I _I	V _{CC} = 0 to 5.5 V, V _I = V _{CC} or GND		±1			±1		±1		μA	
I _{OZPU}	V _{CC} = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$		±50			±50		±50		μA	
I _{OZPD}	V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$		±50			±50		±50		μA	
I _{OZH} ‡	V _{CC} = 2.1 V to 5.5 V, V _O = 2.7 V, $\overline{OE} \geq 2$ V		10			10		10		μA	
I _{OZL} ‡	V _{CC} = 2.1 V to 5.5 V, V _O = 0.5 V, $\overline{OE} \geq 2$ V		-10			-10		-10		μA	
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V		±100					±100		μA	
I _{CEX}	Outputs high	V _{CC} = 5.5 V, V _O = 5.5 V	50			50		50		μA	
I _O §	V _{CC} = 5.5 V, V _O = 2.5 V		-25	-75	-100	-25	-100	-25	-100	mA	
I _{CC}	Outputs high	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND		2			2		2		mA
	Outputs low			32			32		32		
	Outputs disabled			2			2		2		
ΔI _{CC} ¶	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	Outputs enabled	1			1.5		1		mA
			Outputs disabled	0.05			1		0.05		
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	1.5			1.5		1.5			
C _i	V _I = 2.5 V or 0.5 V		3.5							pF	
C _o	V _O = 2.5 V or 0.5 V		8							pF	

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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SN54ABT162827, SN74ABT162827
20-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ$ C			SN54ABT162827		SN74ABT162827		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.1	3.6	1	4.1	1	3.9	ns
t_{PHL}			1.1	2.8	4.2	1.1	5	1.1	4.7	
t_{PZH}	\overline{OE}	Y	1.5	3.4	6.3	1.5	7.2	1.5	6.9	ns
t_{PZL}			1.6	3.5	7.3	1.6	6.6	1.6	6.3	
t_{PHZ}	\overline{OE}	Y	2.1	4.1	6.5	2.1	6.8	2.1	6.6	ns
t_{PLZ}			1.5	3.5	5.9	1.5	7.3	1.5	6.3	

† All typical values are at $V_{CC} = 5$ V.

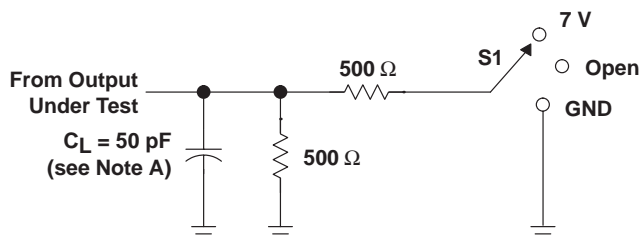
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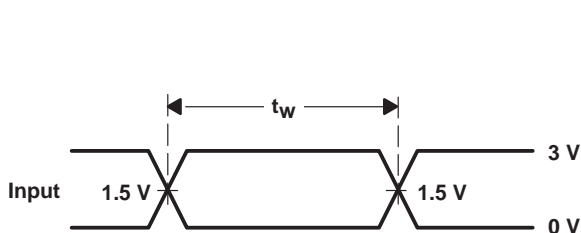
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PARAMETER MEASUREMENT INFORMATION

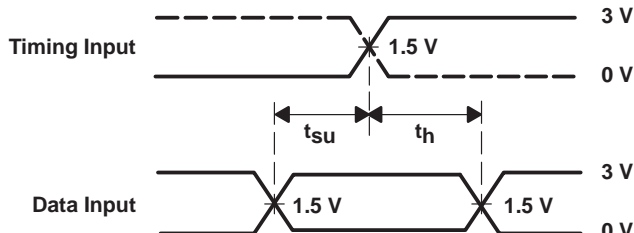


LOAD CIRCUIT FOR OUTPUTS

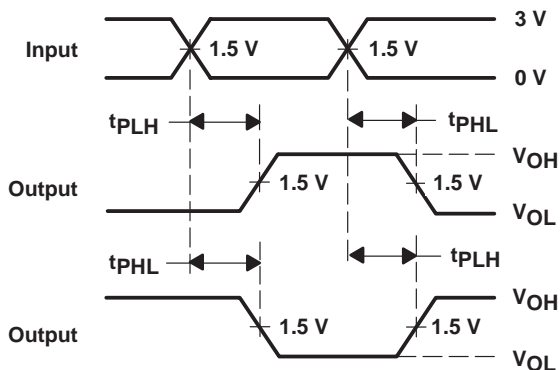
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



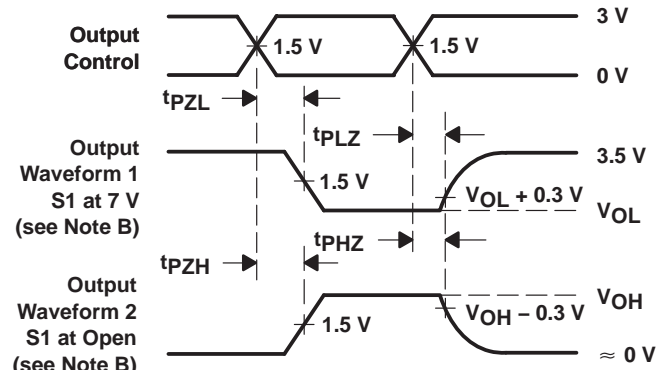
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT162827DGGR	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI
SN74ABT162827DL	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI
SN74ABT162827DLR	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
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 D. Falls within JEDEC MO-118

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